

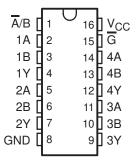
EN: This Datasheet is presented by the manufacturer.

Please visit our website for pricing and availability at www.hestore.hu.

SCLS071D - NOVEMBER 1988 - REVISED OCTOBER 2003

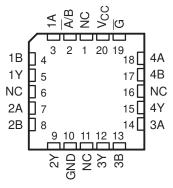
- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current Outputs Drive Up To 15 LSTTL Loads
- Typical t<sub>pd</sub> = 15 ns
- Low Power Consumption, 80-μA Max I<sub>CC</sub>

SN54HCT157 ... J OR W PACKAGE SN74HCT157 ... D OR N PACKAGE (TOP VIEW)



- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- Buffered Inputs and Outputs

### SN54HCT157...FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

These data selectors/multiplexers contain inverters and drivers to supply full data selection to the four output gates. A separate strobe  $(\overline{G})$  input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs.

#### **ORDERING INFORMATION**

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HCT157N	SN74HCT157N
4000 +- 0500		Tube of 40	SN74HCT157D	
-40°C to 85°C	SOIC - D	Reel of 2500	SN74HCT157DR	HCT157
		Reel of 250	SN74HCT157DT	
	CDIP – J	Tube of 25	SNJ54HCT157J	SNJ54HCT157J
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HCT157W	SNJ54HCT157W
	LCCC – FK	Tube of 55	SNJ54HCT157FK	SNJ54HCT157FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

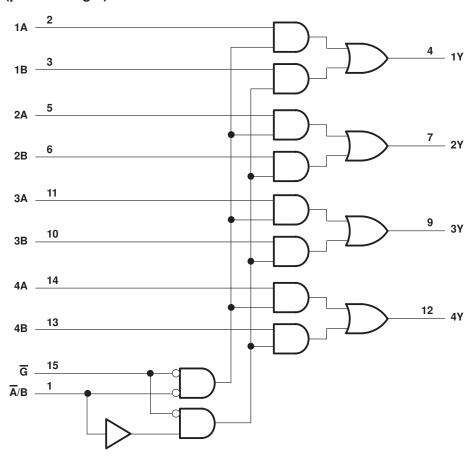


SCLS071D - NOVEMBER 1988 - REVISED OCTOBER 2003

#### **FUNCTION TABLE**

	INPUTS										
STROBE	SELECT	SELECT DATA									
G	Ā/B	Α	В	·							
Н	Х	Χ	Х	L							
L	L	L	X	L							
L	L	Н	X	Н							
L	Н	Χ	L	L							
L	Н	Х	Н	Н							

#### logic diagram (positive logic)



Pin numbers shown are for the D, J, N, and W packages.

SCLS071D - NOVEMBER 1988 - REVISED OCTOBER 2003

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to	7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20	) mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±20	) mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±35	5 mA
Continuous current through V <sub>CC</sub> or GND	±70	) mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	73°	C/W
N package	67°	C/W
Storage temperature range, T <sub>Stg</sub>	-65°C to 15	50°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

			SN	54HCT1	57	SN	74HCT1	57	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2	Š	7/	2			V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		PA	0.8			0.8	V
VI	Input voltage		0	1	VCC	0		VCC	V
VO	Output voltage		0	3	VCC	0		$V_{CC}$	V
t <sub>t</sub>	Input transition (rise and fall) time		0~	Š	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	7507.001	IDITIONS	.,	Т	A = 25°C	;	SN54H	CT157	SN74H	CT157	
PARAMETER	TEST CON	IDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
V	V VV	I <sub>OH</sub> = -20 μA	451/	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	3	3.84		V
V	V V 20V	I <sub>OL</sub> = 20 μA	451/		0.001	0.1		0.1		0.1	
V <sub>OL</sub>	$V_I = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4		0.33	V
lį	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100	1	±1000		±1000	nA
lcc	$V_I = V_{CC} \text{ or } 0,$	IO = 0	5.5 V			8	2	160		80	μΑ
ΔI <sub>CC</sub> †	One input at 0.5 V or 2.4 V, Other inputs at 0 or V <sub>CC</sub>		5.5 V		1.4	2.4	PRO/	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10*		10	pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

SCLS071D - NOVEMBER 1988 - REVISED OCTOBER 2003

## switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	,,	T	չ = 25°C	;	SN54HCT157	SN74HCT157	LINUT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT
	A or D	V	4.5 V		18	28	42	35	
	A or B	Y	5.5 V		15	25	38	32	
	Ā/B	V	4.5 V		20	32	48	40	
<sup>t</sup> pd	A/B	Y	5.5 V		17	29	43	36	ns
	G	V	4.5 V		18	26	39	33	
	G	Y	5.5 V		15	23	35	30	
+.		Any	4.5 V		8	15	22	19	no
·ţ	t <sub>t</sub>	Any	5.5 V		7	14	21	17	ns

## switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

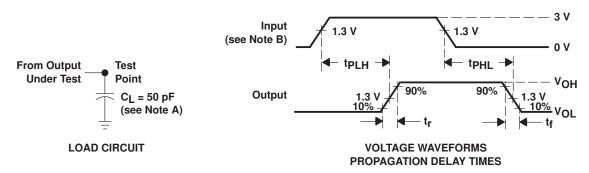
DADAMETED	FROM	то	,	T,	ղ = 25°C	;	SN54H	CT157	SN74H	CT157	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A au D	Υ	4.5 V		23	42		63		52	
	A or B	Y	5.5 V 19 38				52		46		
	Ā/B	Υ	4.5 V		24	46		472		58	
<sup>t</sup> pd	A/B		5.5 V		21	41	7	61		52	ns
	0	V	4.5 V 21		39	$\mathcal{O}_{\mathcal{I}_{\mathcal{I}}}$	58		48		
	G	Y	5.5 V		19	35	20	49		43	
+.		Any	4.5 V		17	42	Q	63		53	20
t <sub>t</sub>		Any	5.5 V		14	38		57		48	ns

#### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Ср	Power dissipation capacitance	No load	12	рF

SCLS071D - NOVEMBER 1988 - REVISED OCTOBER 2003

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50~\Omega$ ,  $t_f = 6$  ns,  $t_f = 6$  ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpl H and tpHI are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 13-Aug-2021

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing		Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HCT157D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT157	Samples
SN74HCT157DE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT157	Samples
SN74HCT157DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT157	Samples
SN74HCT157DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT157	Samples
SN74HCT157DRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT157	Samples
SN74HCT157DT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT157	Samples
SN74HCT157N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT157N	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



#### PACKAGE OPTION ADDENDUM

www.ti.com 13-Aug-2021

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### **PACKAGE MATERIALS INFORMATION**

www.ti.com 5-Jan-2022

#### TAPE AND REEL INFORMATION



# TAPE DIMENSIONS KO P1 BO W Cavity AO

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT157DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 5-Jan-2022



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT157DR	SOIC	D	16	2500	340.5	336.1	32.0

#### PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

#### **TUBE**

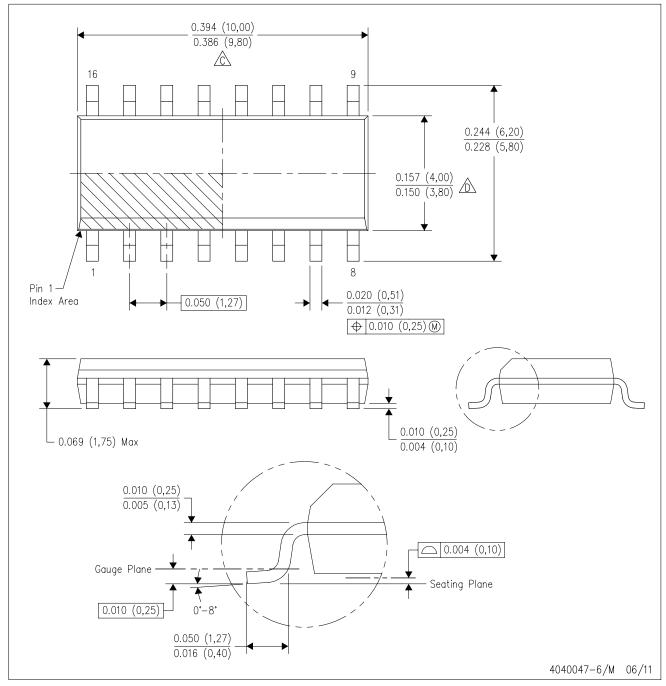


#### \*All dimensions are nominal

7 III dilitational dia manifesta								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HCT157D	D	SOIC	16	40	507	8	3940	4.32
SN74HCT157DE4	D	SOIC	16	40	507	8	3940	4.32
SN74HCT157N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HCT157N	N	PDIP	16	25	506	13.97	11230	4.32

#### D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



## D (R-PDSO-G16)

#### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### N (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated